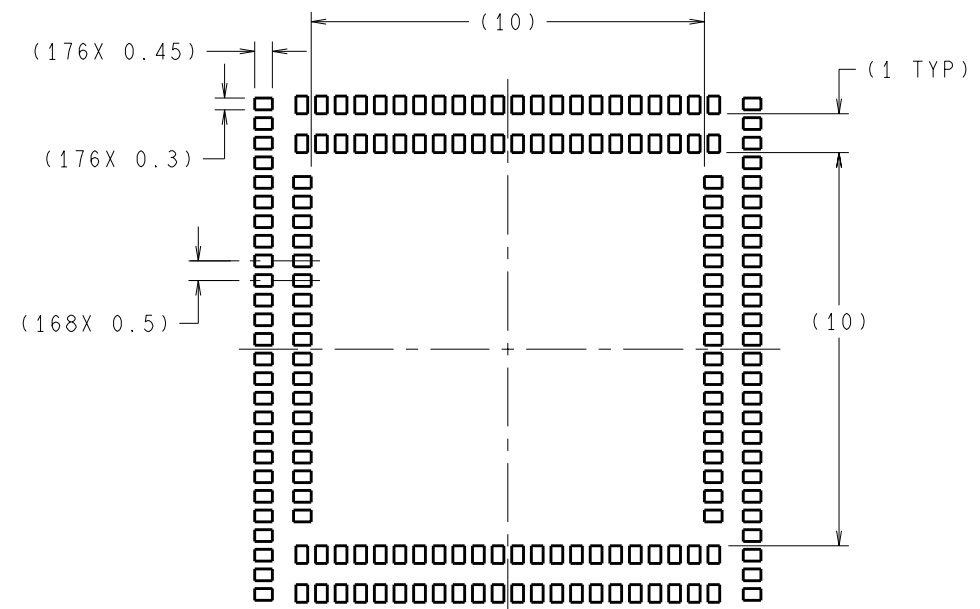
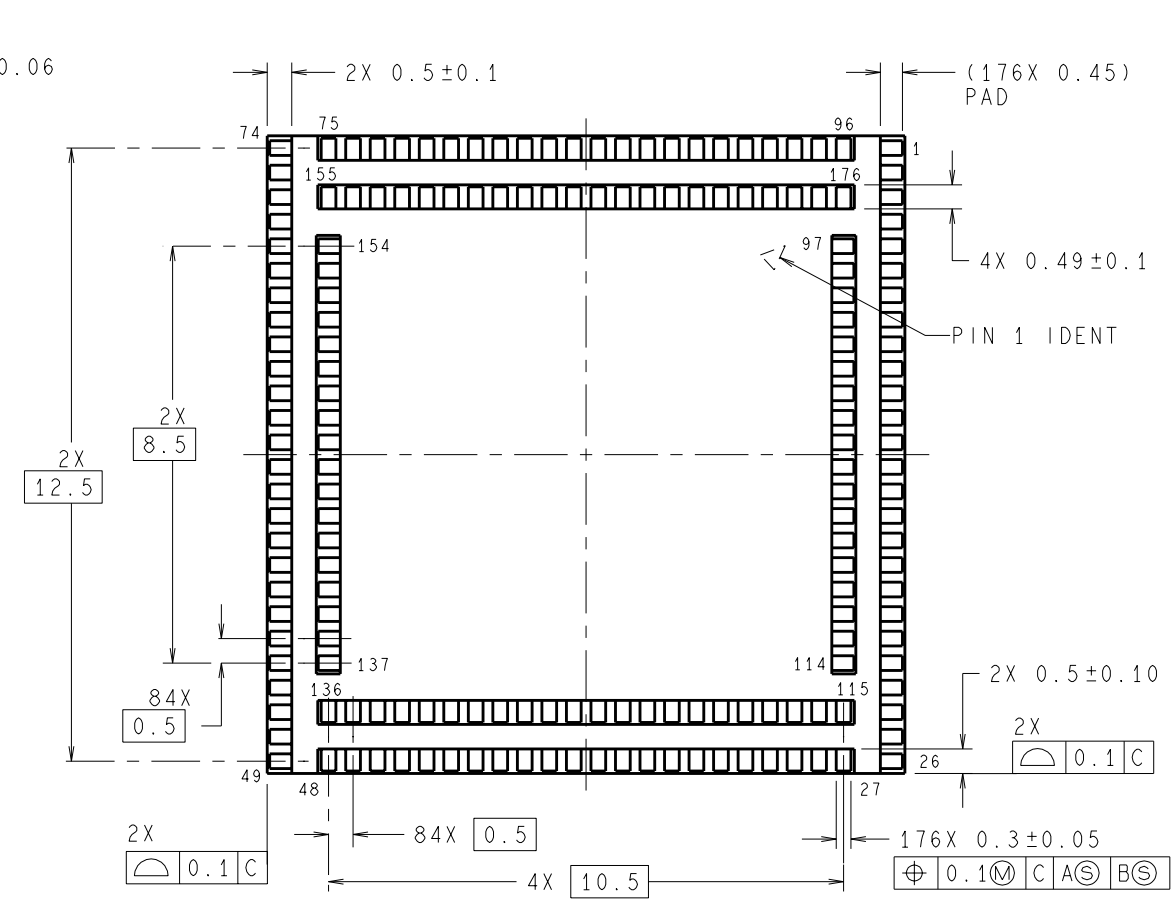
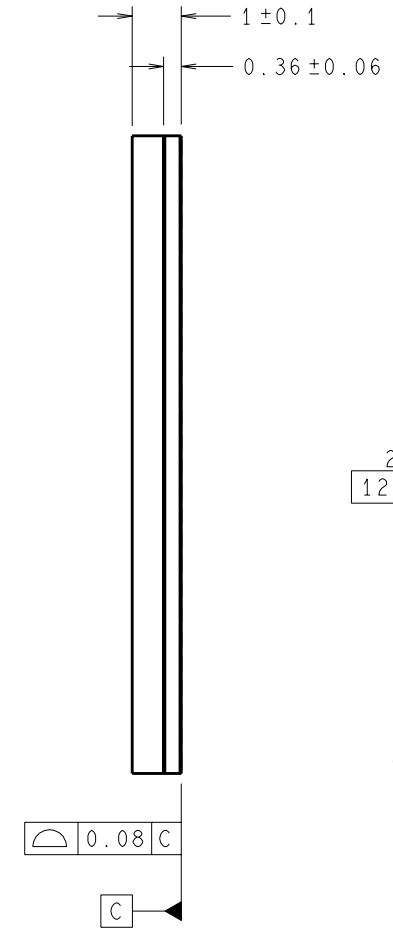
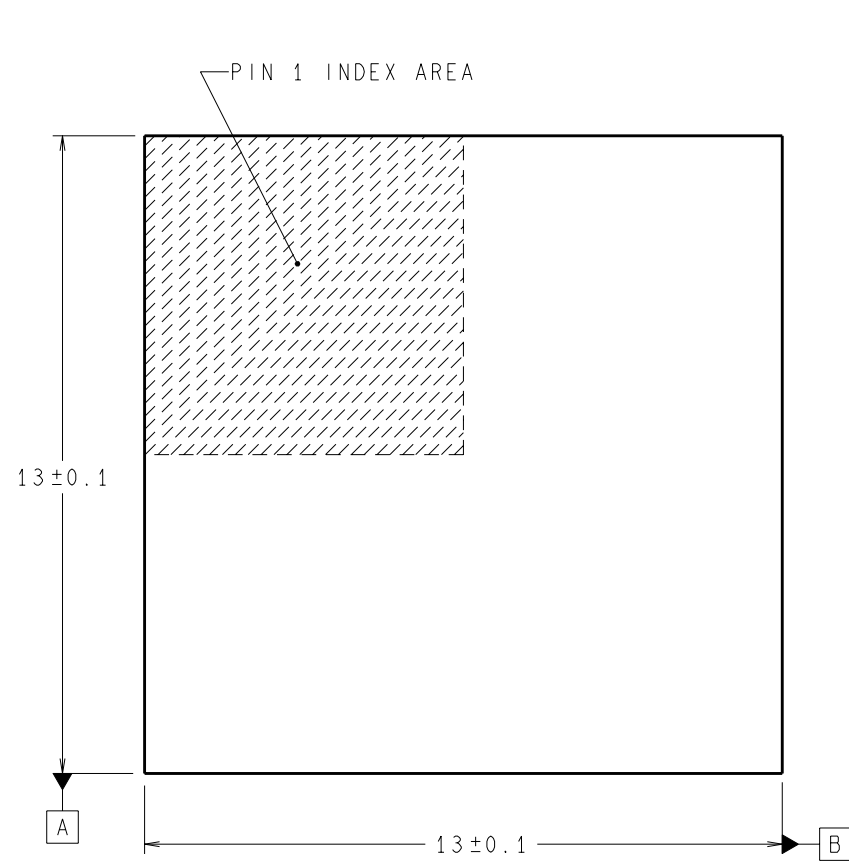


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	141	08/23/2000	TL/WL



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS



- NOTES: UNLESS OTHERWISE SPECIFIED.
- MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
 - PLATING: Cu 15 TO 20 MICROMETERS (FULL)
Ni 10 ± 5 MICROMETERS (LEADS ONLY)
Au 1 ± 0.5 MICROMETER (LEADS ONLY)
 - REFERENCE JEDEC MO-208, VARIATION UUEB, DATED DECEMBER 1999.

APPROVALS		DATE	National Semiconductor		
DRAWN T. LEQUANG		08/23/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. MARTA SUCHY		08/23/2000	CSP, PLASTIC, LAMINATED, 13 x 13 x 1 mm BODY, 176 L, 0.5 mm PITCH		
ENGR. CHK. WAYNE LEE		08/23/2000			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLB176A	A
INCH [MM]		FORMERLY: N/		SHEET 1 of 1	